Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	3 X 3 X 0.85 (1.5 EP)
Lead Count	12
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	6.52E-03	86.91	869100	29.96	299552
Thermosets	Epoxy & Phenol Resin	Proprietary	9.59E-04	12.78	127800	4.40	44049
Other inorganic materials	Carbon black	1333-86-4	2.33E-05	0.31	3100	0.11	1068
Subtotal			7.50 E-03	100.00	1000000	34.47	344669

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.24 E-02	97.50	975000	56.86	568601
Copper & its alloys	Iron	7439-89-6	2.98 E-04	2.35	23500	1.37	13705
Copper & its alloys	Zinc	7440-66-6	1.52 E-05	0.12	1200	0.07	700
Copper & its alloys	Phosphorus	7723-14-0	3.81 E-06	0.03	300	0.02	175
Subtotal			1.27 E-02	100.00	1000000	58.32	583180

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.90 E-04	100.0	1000000	1.33	13327

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.80 E-04	100.0	1000000	1.75	17463

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.70 E-04	100.0	1000000	0.78	7813

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.80 E-04	100.0	1000000	2.21	22059

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.84 E-04	73.40	734000	0.84	8433
Thermoset	Epoxy Resin	Proprietary	4.59 E-05	18.35	183500	0.21	2108
Other inorganic materials	Metal oxide	Proprietary	6.88 E-06	2.75	27500	0.03	316
Others	Curing and hardening agent	Proprietary	6.88 E-06	2.75	27500	0.03	316
Other organic materials	Gamma Butyrolactone	96-48-0	6.88 E-06	2.75	27500	0.03	316
Subtotal			2.50 E-04	100.0	1000000	1.15	11489

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.18 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary